



## Description

### JMT N-channel Enhancement Mode Power MOSFET

#### Features

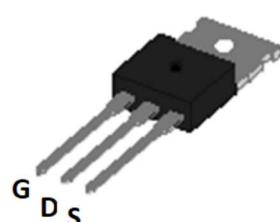
- 80V, 80A
- $R_{DS(ON)} < 9m\Omega$  @  $V_{GS} = 10V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

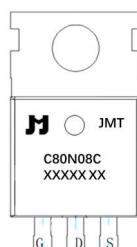
- Load Switch
- PWM Application
- Power management



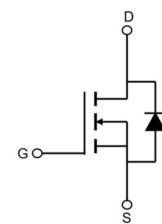
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



TO-220C top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	TUBE (PCS)	Inner Box (PCS)	Per Carton (PCS)
JMTC80N08C	JMTC80N08C	TUBE	TO-220C	50	1,000	8,000

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise specified)

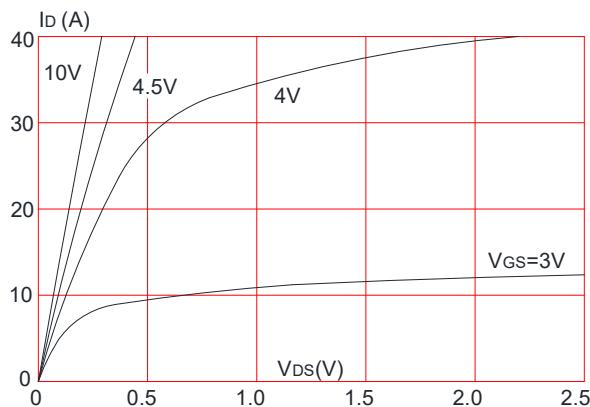
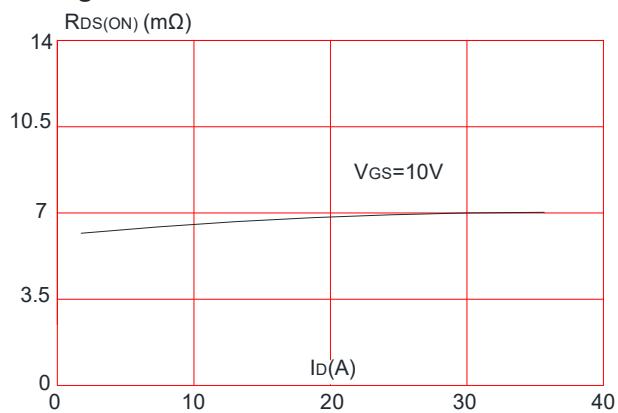
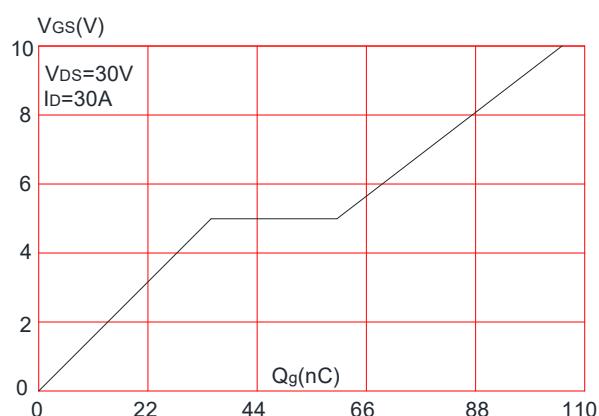
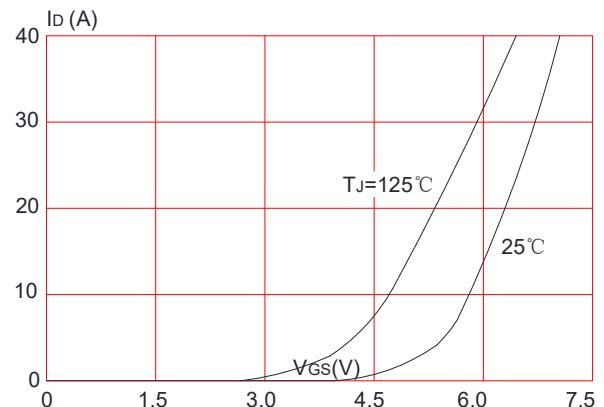
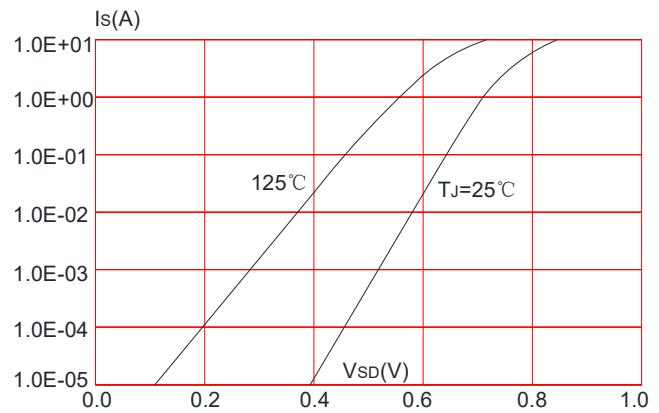
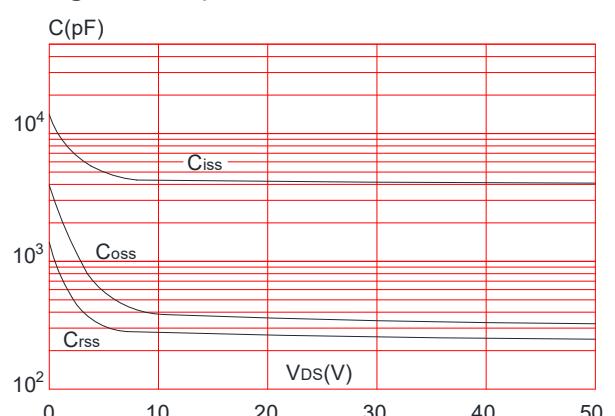
Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		80	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ C$	80	A
		$T_c = 100^\circ C$	52	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		320	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		603	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ C$	105	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.43	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

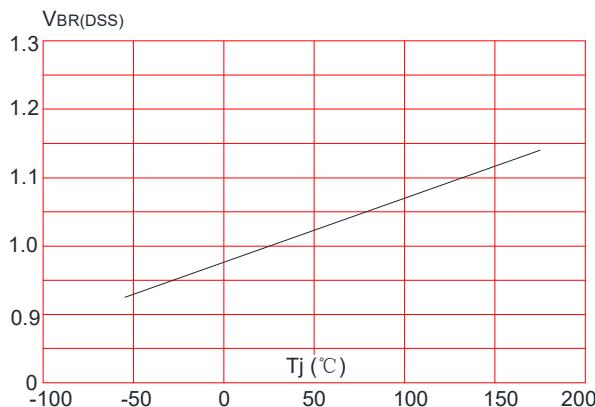
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	80	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=80\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	2.0	2.8	4.0	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note3	$V_{GS}=10\text{V}$ , $I_D=30\text{A}$	-	7	9	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	4045	-	pF
$C_{oss}$	Output Capacitance		-	326	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	234	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30\text{V}$ , $I_D=30\text{A}$ , $V_{GS}=10\text{V}$	-	106	-	nC
$Q_{gs}$	Gate-Source Charge		-	35	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	25	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30\text{V}$ , $I_D=30\text{A}$ , $R_G=1.8\Omega$ , $V_{GS}=10\text{V}$	-	28	-	ns
$t_r$	Turn-on Rise Time		-	55	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	69	-	ns
$t_f$	Turn-off Fall Time		-	27	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	80	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	320	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=30\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=30\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	37	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	52	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

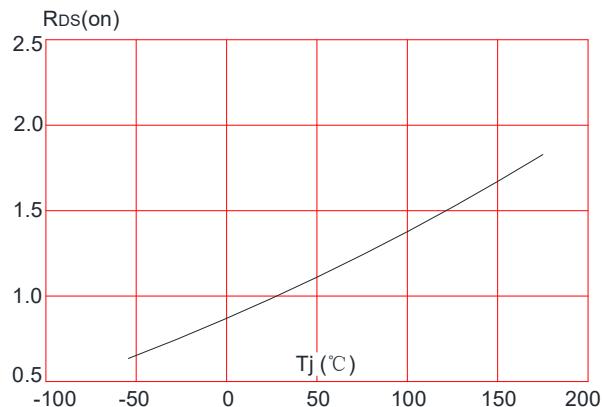
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30\text{V}$ ,  $V_G=10\text{V}$ ,  $L=1.54\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=28\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

**Figure1:** Output Characteristics

**Figure 3:** On-resistance vs. Drain Current

**Figure 5:** Gate Charge Characteristics

**Figure 2:** Typical Transfer Characteristics

**Figure 4:** Body Diode Characteristics

**Figure 6:** Capacitance Characteristics


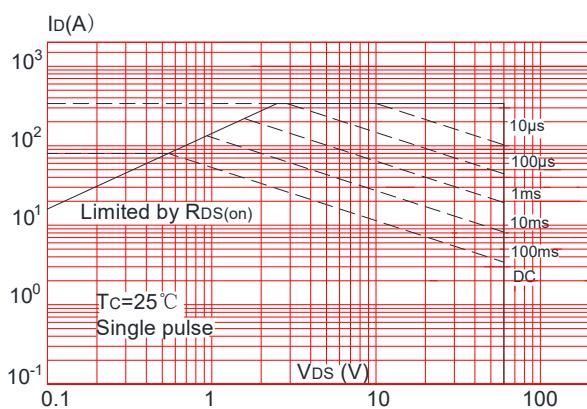
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



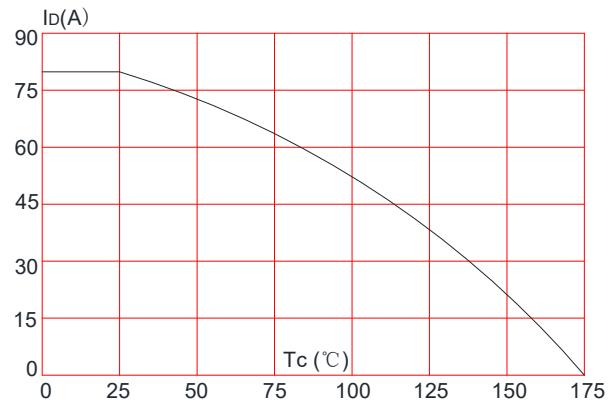
**Figure 8:** Normalized on Resistance vs. Junction Temperature



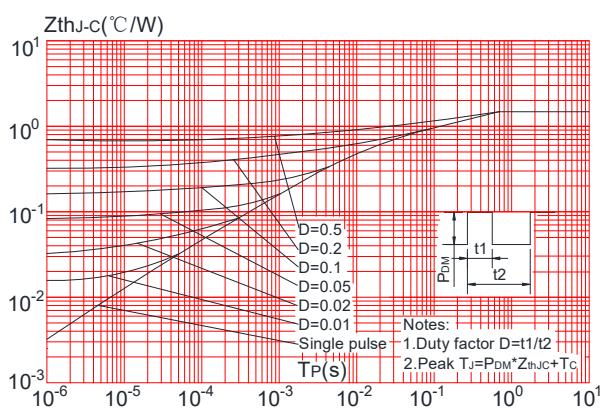
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## Test Circuit

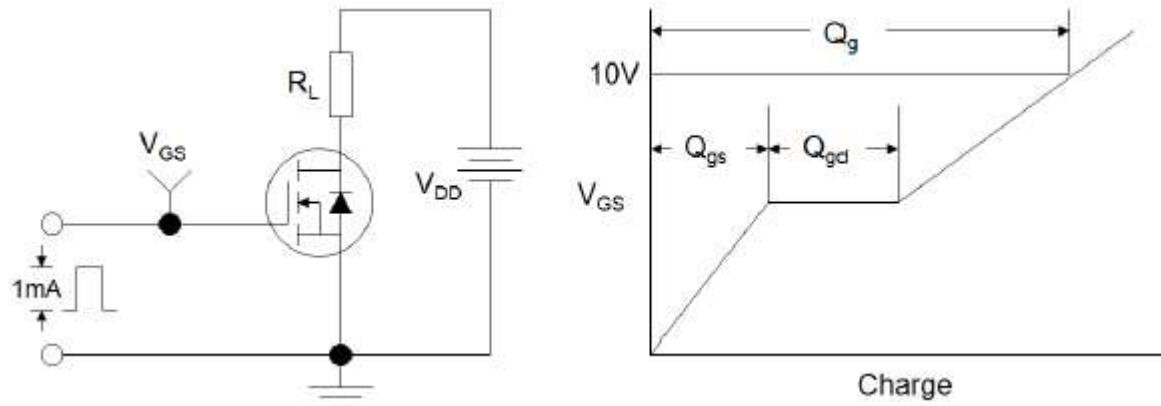


Figure1:Gate Charge Test Circuit & Waveform

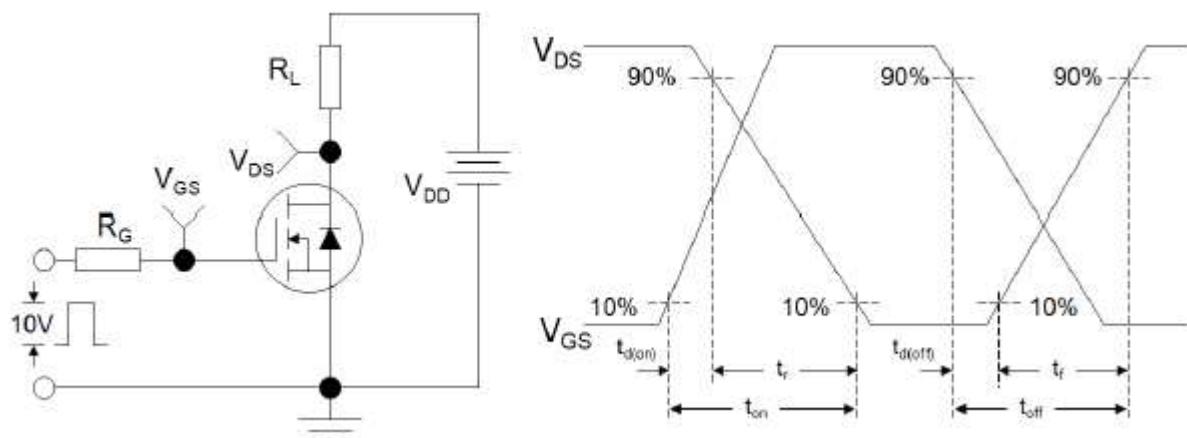


Figure 2: Resistive Switching Test Circuit & Waveforms

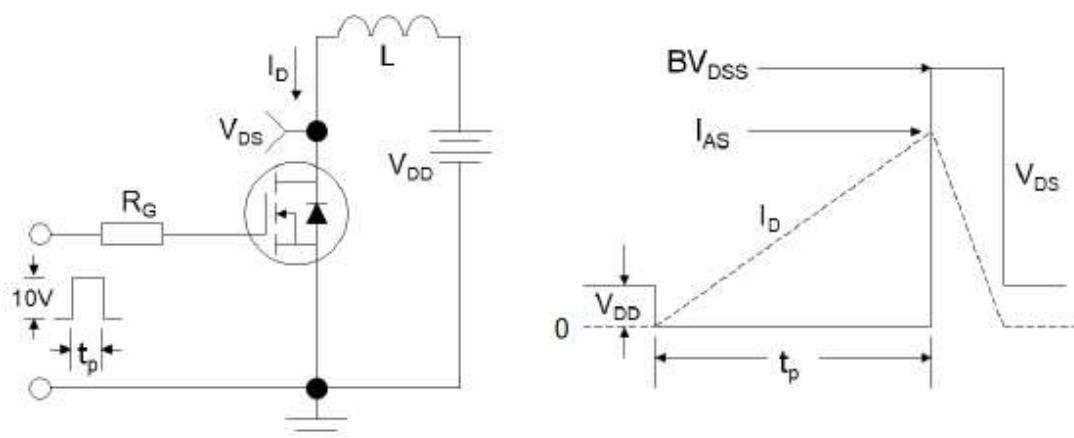
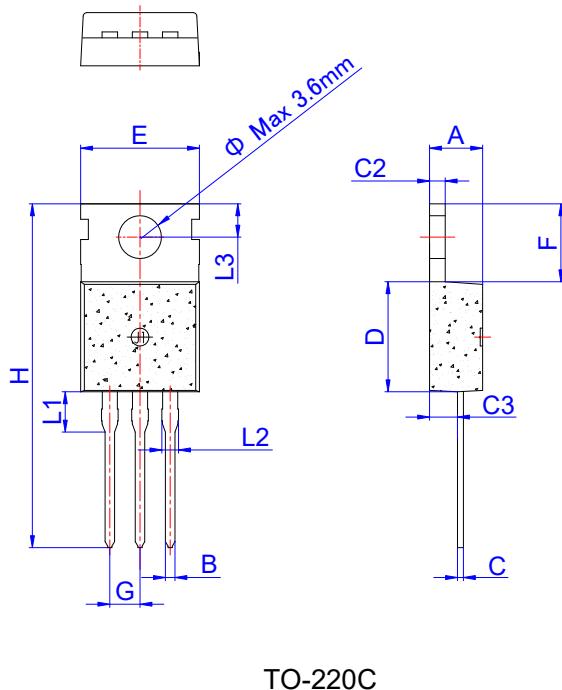


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data- TO-220C



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.70		0.90	0.028		0.035
C	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.90		9.90	0.350		0.390
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.39			0.133	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

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